

• General Description

It combines trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Low $R_{DS(ON)}$ to minimize conductive loss
- High GOX reliability
- Low Thermal resistance

• Application

- BLDC Motor driver
- DC-DC
- Load Switch

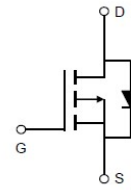
• Ordering Information:

Part NO.	ZM020KP10D
Marking	ZM020KP10
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

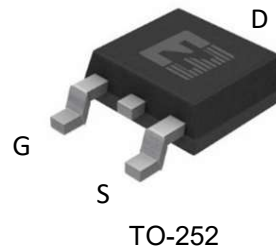
• Absolute Maximum Ratings ($T_C=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		-100	V
Gate-Source Voltage ^①	V_{GS}		±20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	-8	A
	I_D	$T_C=75^\circ\text{C}$	-7	A
	I_D	$T_C=100^\circ\text{C}$	-6	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$;	-24	A
Total Power Dissipation	P_D	$T_C=25^\circ\text{C}$	68	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	2.4	W
Operating Junction Temperature	T_J		-55 to +175	°C
Storage Temperature	T_{STG}		-55 to +175	°C
Single Pulse Avalanche Energy	E_{AS}	L=0.1mH, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	5	mJ
		L=0.5mH, $V_{GS}=-10\text{V}$, $R_g=25\Omega$,	9.5	mJ
ESD Level (HBM)	CLASS 1C			

• Product Summary



$V_{DS} = -100\text{V}$
 $R_{DS(ON)} = 200\text{m}\Omega$
 $I_D = -8\text{A}$



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	2.2	°C/W
Thermal resistance, junction-ambient ^②	R_{thJA}		-	62	°C/W
Soldering temperature	T_{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = -250\mu A$	-100			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = -250\mu A$	-1.3	-1.8	-2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS} = 0V, V_{DS} = -100V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = -10V, I_D = -8A$		200	245	m Ω
		$V_{GS} = -4.5V, I_D = -6A$		220	265	m Ω
Forward Transconductance	g_{FS}	$V_{DS} = -5V, I_{SD} = -4A$		6		S
Diode Forward Voltage	V_{FSD}	$V_{GS} = 0V, I_{SD} = -8A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f = 1MHz, V_{DS} = -25V$	-	1670	-	pF
Output capacitance	C_{oss}		-	88	-	
Reverse transfer capacitance	C_{rss}		-	49	-	
Gate Resistance	R_g	$f = 1MHz$	-	8		Ω
Total gate charge	Q_g	$V_{DD} = -15V, I_D = -8A, V_{GS} = -10V$	-	22.4	-	nC
	$Q_g(-4.5v)$		-	10	-	
Gate - Source charge	Q_{gs}		-	4.2	-	
Gate - Drain charge	Q_{gd}		-	2.8	-	
Turn-ON Delay time	$t_{D(on)}$		-	17	-	
Turn-ON Rise time	t_r	$V_{GS} = -10V, V_{DS} = -15V, R_G = 3.3\Omega, I_D = -10A$	-	62	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	45	-	ns
Turn-Off Fall time	t_f		-	46	-	ns

Fig.1 Gate-Charge Characteristics

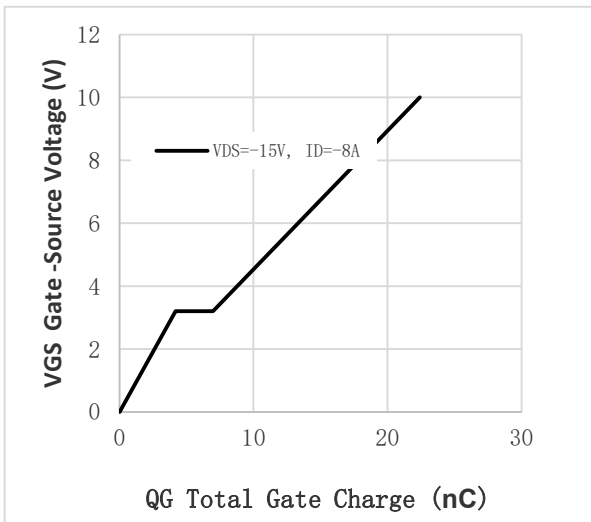


Fig.2 Capacitance Characteristics

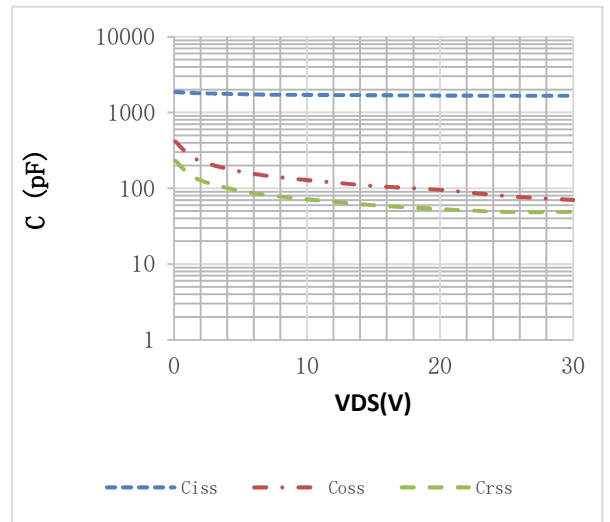


Fig.3 Power Dissipation

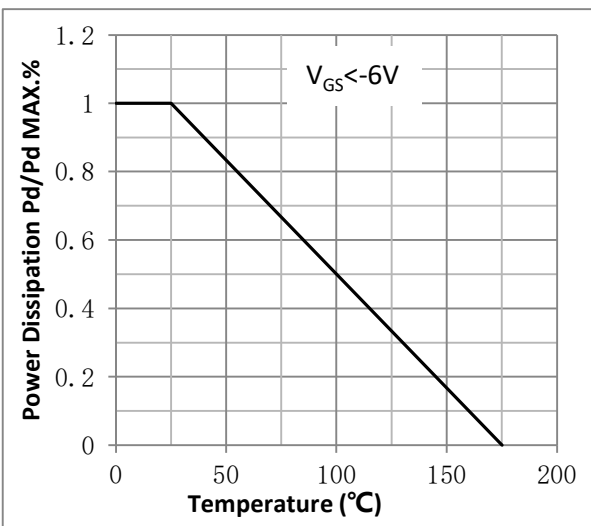


Fig.4 Typical output Characteristics

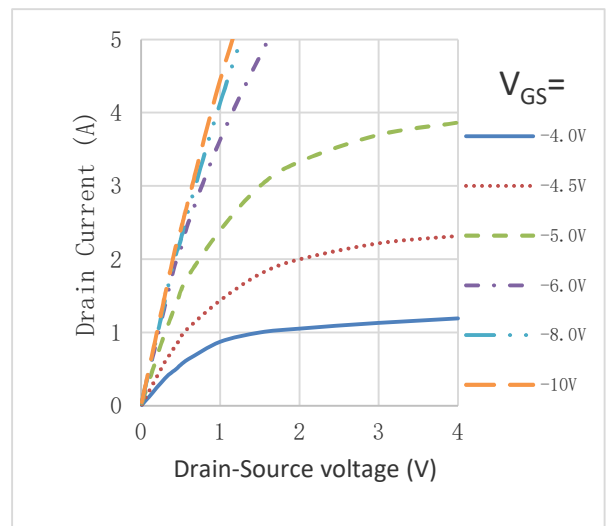


Fig.5 Threshold Voltage V.S Junction Temperature

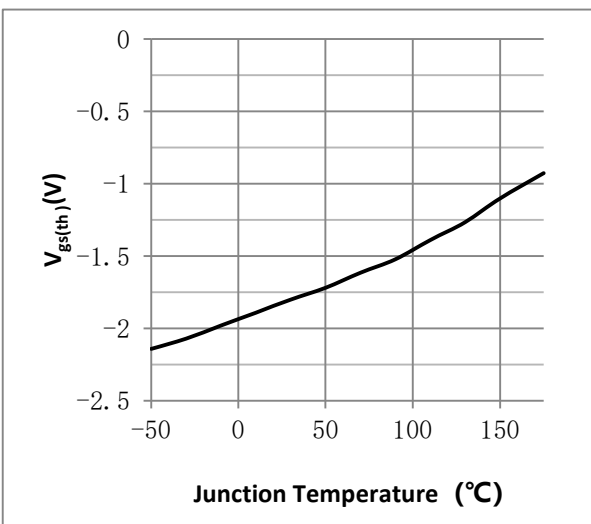


Fig.6 Resistance V.S Drain Current

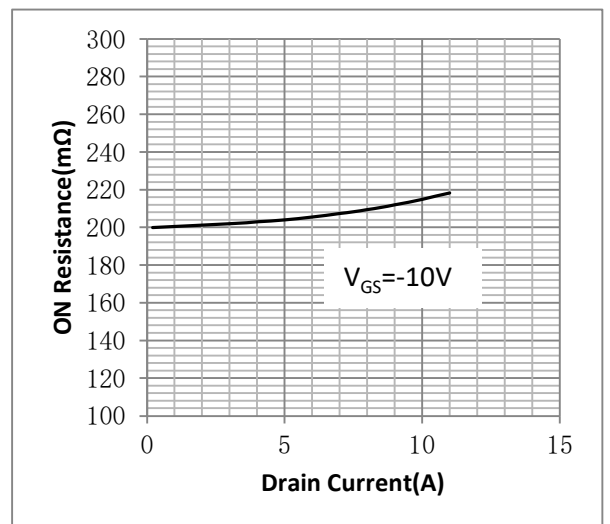


Fig.7 On-Resistance VS Gate Source Voltage

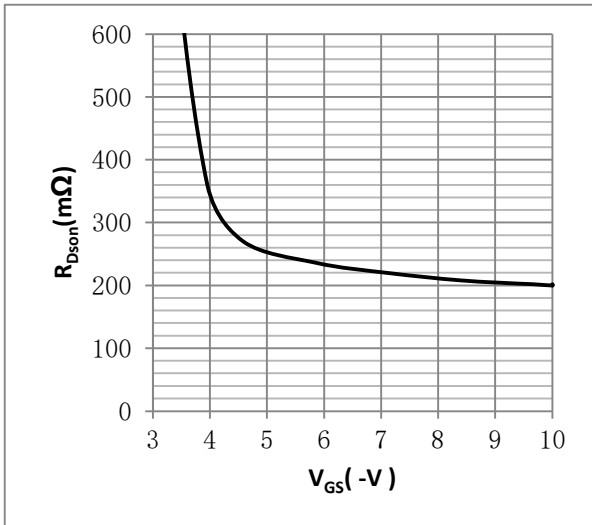


Fig.8 On-Resistance V.S Junction Temperature

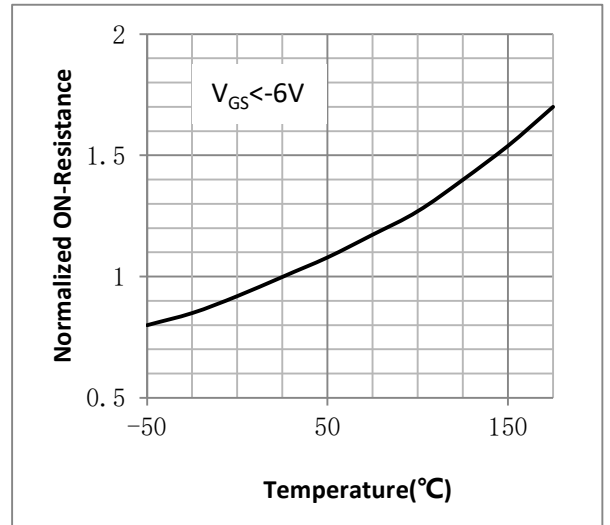


Figure 9. Diode Forward Voltage vs. Current

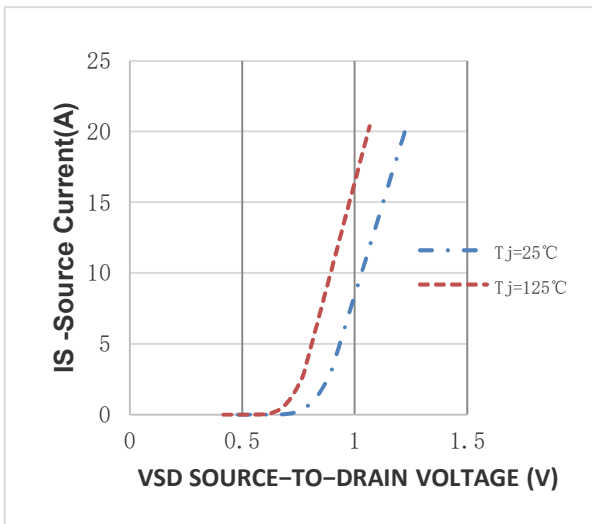


Figure 10. Transfer Characteristics

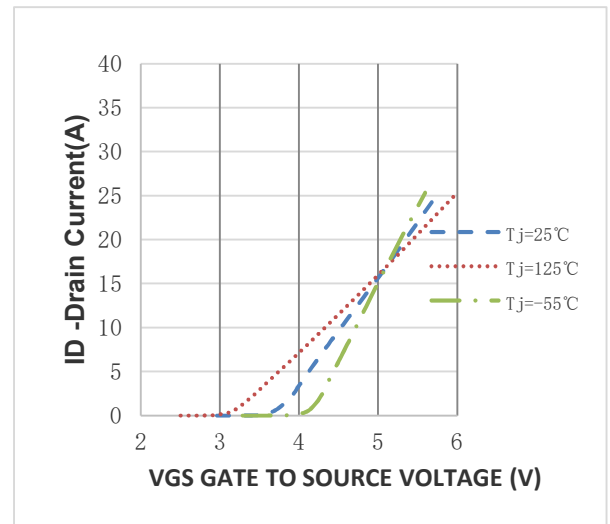


Fig.11 Safe Operating Area

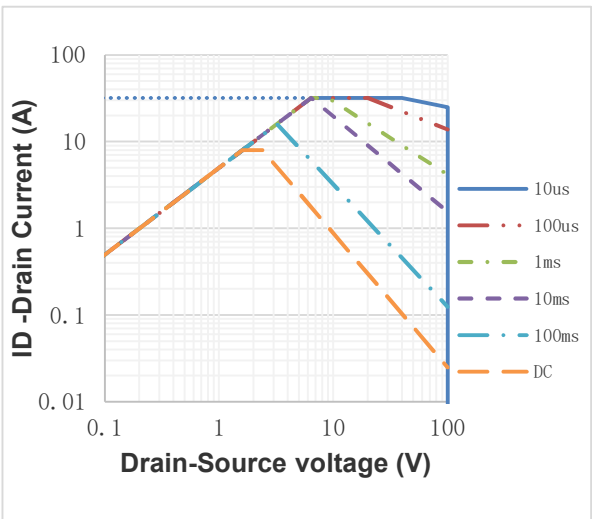
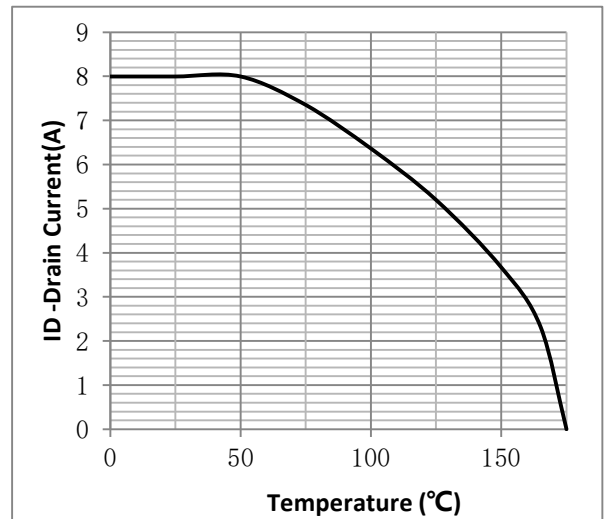
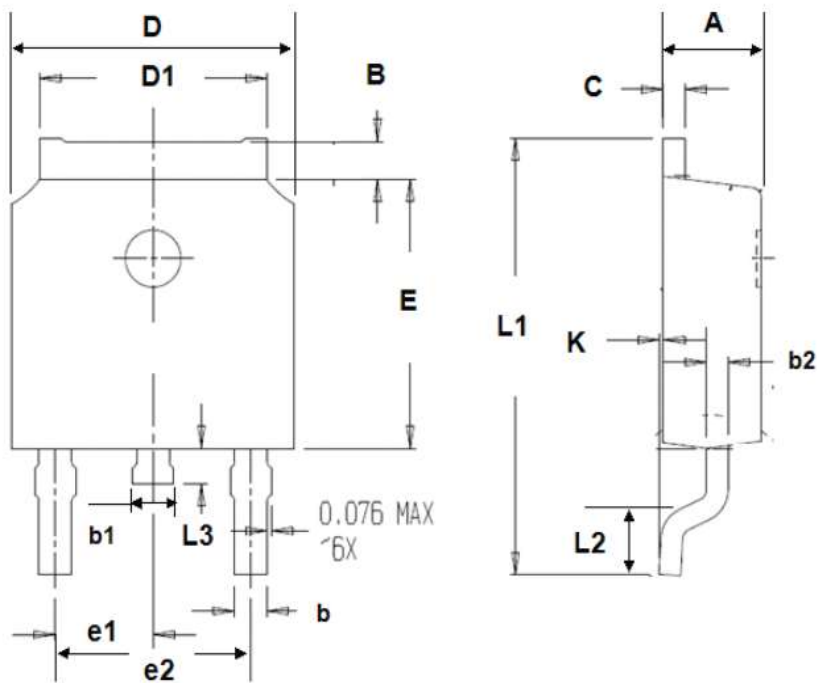


Fig.12 ID vs. Case Temperature^③



•TO-252 Package Outline

SYMBOL	min	max	SYMBOL	min	max
A	2.1	2.5	B	0.85	1.25
b	0.5	0.8	b1	0.5	0.9
b2	0.45	0.7	C	0.45	0.7
D	6.3	6.75	D1	5.1	5.5
E	5.3	6.3	e1	2.25	2.35
L1	9.2	10.6	e2	4.45	4.75
L2	0.9	1.75	L3	0.6	1.1
K	0	0.23			



Note:

- ① Pulse : $V_{GS}=+20V/-20V$, Duty cycle=50%, $T_j=175^{\circ}C$, $t=1000$ hours; For DC , the following test conditions can be passed: $V_{GS}=-20V/+10V$, $T_j=175^{\circ}C$, $t=1000$ hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=-10V$.

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Revision History

Version	Date	Change
A	2021.8.12	NEW
B	2021.9.7	Add ESD LEVEL
C	2023.12.23	1.Add dynamic characteristics. 2.Correct characteristic curves.
D	2024.5.10	Correct Qg current